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EIA STANDARD

TP-56E

Resistance to Soldering Heat Test Procedure for Electrical Connectors and Sockets

EIA-364-56E

(Revision of EIA-364-56D)

November 2011



Electronic Components Industry Association

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(From Standards Proposal No. 5492.06, formulated under the cognizance of the CE-2.0 Committee on EIA National Connector and Sockets Standards)

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CONTENTS

Clause		Page
1	Introduction	1
1.1	Scope	1
1.2	Object	1
1.3	Reference documents	1
2	Test resources	2
2.1	Equipment	2
2.2	Material	3
3	Test specimen	3
3.1	Description	3
3.2	Preparation	3
4	Test procedure	3
4.1	General for Procedure 1 and 2 only	4
4.2	Procedure 1, solder cup	4
4.3	Procedure 2, solder eyelet tab or post	4
4.4	Procedure 3, dip and wave solder	5
4.5	Procedure 5, infrared reflow; or Procedure 6, convection reflow	6
5	Details to be specified	8
6	Test documentation	8
Table		
1	Test conditions	6
2	Test levels	7
Annex		
A	Normative	A-1

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